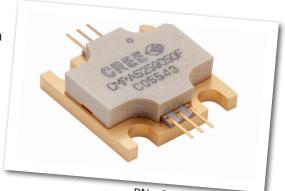


CMPA5259050F

50 W, 5200 - 5900 MHz, 28 V, GaN MMIC for Radar Power Amplifiers

Cree's CMPA5259050F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) designed specifically for high efficiency, high gain, and wide bandwidth capabilities, which makes CMPA5259050F ideal for 5.2 - 5.9 GHz Radar amplifier applications. The transistor is supplied in a 0.5 inch square ceramic/metal flange package.



PN: CMPA5259050F Package Type: 440219

Typical Performance Over 5.2-5.9 GHz ($T_c = 25$ °C) of Demonstration Amplifier

Parameter	5.2 GHz	5.5 GHz	5.9 GHz	Units
Small Signal Gain	31.4	30.8	31.0	dB
Output Power	59.6	56.0	55.2	W
Efficiency	51.5	50.1	51.4	%
Input Return Loss	-12.5	-12.0	-7.0	dB

Note:

100 μ sec Pulse Width, 10% Duty Cycle, P_{IN} = 26 dBm

Features

- 30 dB Small Signal Gain
- 50% Efficiency at P_{SAT}
- Operation up to 28 V
- High Breakdown Voltage
- 0.5 inch-square package

Applications

- AESA Radar
- Defense Radar
- Fire Control Radar
- Naval, Marine, Ground Protection
 Radar
- Weather Radar





Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	$V_{\scriptscriptstyle DSS}$	84	V _{DC}	V_{DC}
Gate-source Voltage	$V_{\sf GS}$	-10, +2	V_{DC}	V_{DC}
Storage Temperature	T_{STG}	-55, +150	°C	°C
Operating Junction Temperature	T _j	225	°C	°C
Soldering Temperature	T_s	245	°C	°C
Screw Torque	τ	60	in-oz	in-oz
Thermal Resistance, Junction to Case ¹	$R_{_{\theta JC}}$	1.60	°C/W	$P_{DISS} = 61 \text{ W, } T_{CASE} = 85^{\circ}\text{C, } 500 \mu\text{s, } 20\%$
Case Operating Temperature	T _c	-40, +105	°C	

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Test Methodology
Human Body Model	НВМ	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	2 (125 V to 250 V)	JEDEC JESD22 C101-C



Electrical Characteristics ($T_c = 25^{\circ}C$)

			İ		i -	
Characteristics DC Characteristics ¹	Symbol	Min.	Тур.	Max.	Units	Conditions
Gate Threshold Voltage	V	-3.0	-2.5		V _{DC}	$V_{DS} = 10 \text{ V}, I_{DS} = 1.0 \text{ A}$
	$V_{GS(th)}$	-3.0		_		
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	V _{DC}	$V_{DS} = 10 \text{ V, I}_{D} = 1.0 \text{ A}$
Saturated Drain Current	\mathbf{I}_{DS}	16.4	18.6	-	А	$V_{DS} = 6 V$, $V_{GS} = 2 V$
Drain-Source Breakdown Voltage	V_{BD}	84	100	-	V_{DC}	$V_{GS} = -8 \text{ V}, I_{DS} = 1.0 \text{ A}$
RF Characteristics ²						
Small Signal Gain ₁	G_{ss}	-	31	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.2 GHz, $P_{IN} = -20$ dBm
Small Signal Gain ₂	G_{SS}	-	31	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.5 GHz, $P_{IN} = -20$ dBm
Small Signal Gain ₃	G_{SS}	-	31	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.9 GHz, $P_{IN} = -20$ dBm
Power Output ₁	P _{out}	-	59.5	-	W	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.2 GHz, $P_{IN} = 26$ dBm
Power Output ₂	P _{out}	-	56	-	W	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.5 GHz, $P_{IN} = 26$ dBm
Power Output ₃	Роит	-	55	-	W	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.9 GHz, $P_{IN} = 26$ dBm
Power Added Efficiency ₁	PAE	-	51	-	%	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.2 GHz, $P_{IN} = 26$ dBm
Power Added Efficiency ₂	PAE	-	50	-	%	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.5 GHz, $P_{IN} = 26$ dBm
Power Added Efficiency ₃	PAE	-	51	-	%	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.9 GHz, $P_{IN} = 26$ dBm
Power Gain ₁	G_{p}	-	21.8	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.2 GHz, $P_{IN} = 26$ dBm
Power Gain ₂	G_{p}	-	21.5	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.5 GHz, $P_{IN} = 26$ dBm
Power Gain ₃	G_{p}	-	21.4	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.9 GHz, $P_{IN} = 26$ dBm
Input Return Loss	S11	-	-12	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.2 - 5.9 GHz, $P_{IN} = -20$ dBm
Output Return Loss	S22	-	-17	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 1.0$ A, Freq = 5.2 - 5.9 GHz, $P_{IN} = -20$ dBm
Output Mismatch Stress	VSWR	-	3:1	-	Ψ	No damage at all phase angles, $V_{DD} = 28 \text{ V}$, $I_{DQ} = 1.0 \text{ A}$, $P_{IN} = 26 \text{ dBm}$

Notes:

 $^{^{\}scriptscriptstyle 1}\mbox{ Measured}$ on wafer prior to packaging.

² Measured in CMPA5259050F-TB test fixture.

³ Drain Efficiency = P_{OUT}/P_{DC}



Typical Pulsed Performance of the CMPA5259050F

Figure 1. - Gain and Input Return Loss vs. Frequency of the CMPA5259050F Measured in CMPA5259050F-AMP Amplifier Circuit

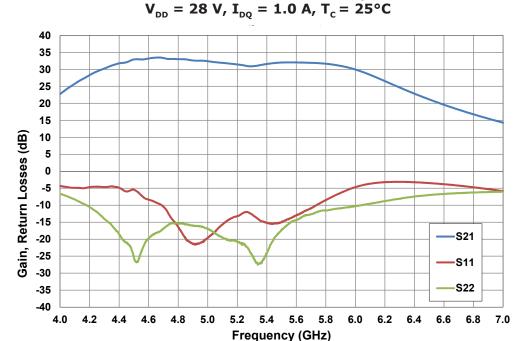
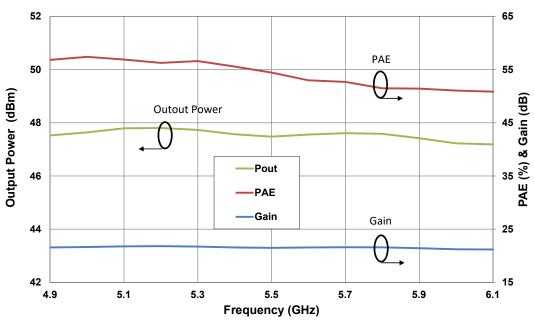


Figure 2. - Output Power, Gain, and Power Added Efficiency vs. Frequency of the CMPA5259050F Measured in CMPA525050F-AMP Amplifier Circuit

$$V_{DD}$$
 = 28 V, I_{DQ} = 1.0 A, P_{IN} = 26 dBm, Pulse Width = 100 µs, Duty Cycle = 10%, T_{C} = 25°C



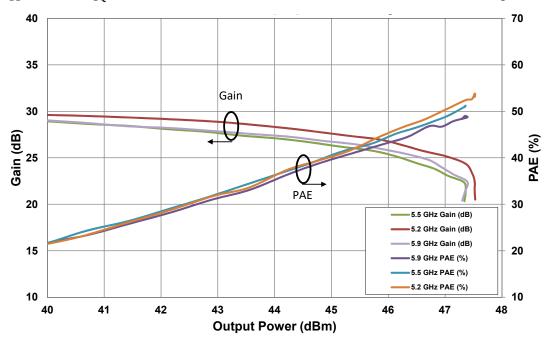
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Typical Pulsed Performance of the CMPA5259050F

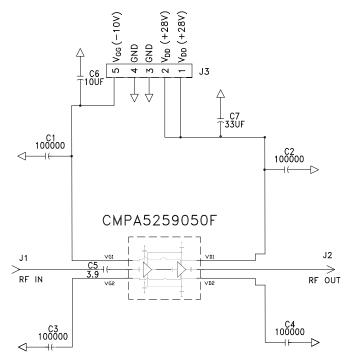
Figure 3. - Gain and Power Added Efficiency vs. Output Power of the CMPA529050F Measured in CMPA525050F-AMP Amplifier Circuit

 $V_{DD} = 28 \text{ V}, I_{DO} = 1.0 \text{ A}, \text{ Pulse Width} = 100 \mu\text{s}, \text{ Duty Cycle} = 10\%, T_{C} = 25^{\circ}\text{C}$

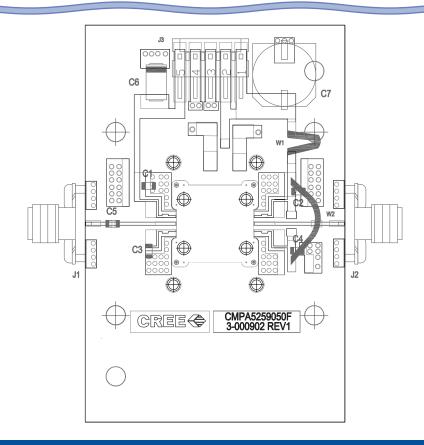




CMPA5259050F-TB Demonstration Amplifier Schematic



CMPA5259050F-TB Demonstration Amplifier Circuit Outline





CMPA5259050F-TB Demonstration Amplifier Circuit Bill of Materials

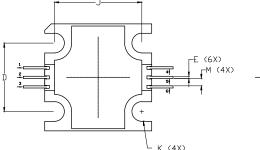
Designator	Description	Qty
R1	RES 0 OHM, SMT, 1206, 125 mW	1
C1, C3, C6, C8	CAP, 100000 pF, (0.1 UF) +/- 10%, 100 V, 0805	4
C2, C4, C5, C7	CAP, 0805, 2200 pF, 100 V, 0805	4
C9	CAP, 10 UF, 16 V, Tantalum	1
C10	CAP, 33 UF, 20%, G Case	1
J3	Header RT> PLZ .1 CEN LK 5POS	1
J1, J2	CONN, SMA, Female, 2-Hole, Flange	2
J4	CONN, SMB, Straight Jack Receptacle, SMT, 50 OHM, Au Plated	1
	Baseplate, AL, 2.60 X 1.7 X 0.25	
	#4 Split Lockwasher SS	
	2-56 SoC HD Screw 3/16 SS	
	#2 Split Lockwasher SS	
	4-40 SOC HD Screw 3/8" SS	
	PCB, Taconics, RF 35, CMPA5259050F 0.010" THK	
W1	Wire, Black, 22 AWG ~ 3"	

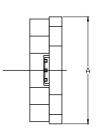
CMPA5259050F-TB Demonstration Amplifier Circuit

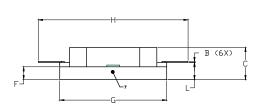


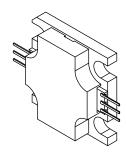


Product Dimensions CMPA5259050F (Package Type — 440219)









NOT TO SCALE

NOTES:

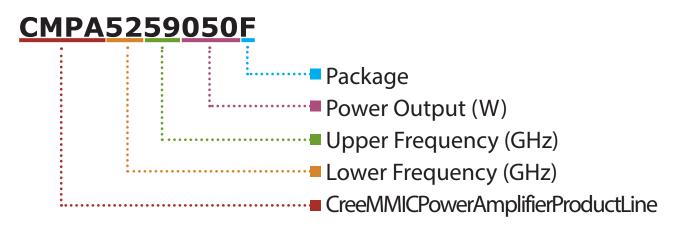
- 1. DIMENSIONING AND TOLERANICING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020' BEYOND EDGE OF LID.
- 4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008' IN ANY DIRECTION.
- 5. ALL PLATED SURFACES ARE NI/AU

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.495	0.505	12.57	12.82
В	0.003	0.005	0.076	0.127
O	0.140	0.160	3.56	4.06
D	0.315	0.325	8.00	8.25
E	0.008	0.012	0.204	0.304
F	0.055	0.065	1.40	1.65
G	0.495	0.505	12.57	12.82
Η	0.695	0.705	17.65	17.91
J	0.403	0.413	10.24	10.49
K	ø .092		2.3	34
L	0.075	0.085	1.905	2.159
М	0.032	0.040	0.82	1.02

PIN	
1	Gate bias
2	RF_{IN}
3	Gate bias
4	Drain bias
5	RF _{OUT}
6	Drain bias
7	Source



Part Number System



Parameter	Value	Units
Lower Frequency	5.2	GHz
Upper Frequency ¹	5.9	GHz
Power Output	50	W
Package	Flange	-

Table 1.

Note¹: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value
А	0
В	1
С	2
D	3
Е	4
F	5
G	6
Н	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

Table 2.



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CMPA5259050F	GaN MMIC	Each	
CMPA5259050F-AMP	Test board with GaN MMIC installed	Each	



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EVAL01-HMC661LC4B EVAL-ADF7020-1DBZ4 EVAL-ADF7020-1DBZ5 EVAL-ADF7020-1DBZ6 EVAL-ADF7021DB9Z EVAL
ADF7021DBJZ EVAL-ADF7021DBZ2 EVAL-ADF7021DBZ6 EVAL-ADF7021-NDBZ2 EVAL-ADF7021-VDB3Z EVAL-ADF7023DB3Z

EVAL-ADF7023-JDB3Z EVAL-ADF70XXEKZ1 EVAL-ADF7241DB1Z F0440EVBI F1423EVB-DI F1423EVB-SI F1701EVBI

F1751EVBI F2250EVBI MICRF219A-433 EV 122410-HMC686LP4E AD6679-500EBZ 126223-HMC789ST89E ADL5363-EVALZ

ADL5369-EVALZ 130437-HMC1010LP4E 131352-HMC1021LP4E 131372-HMC951LP4E 130436-HMC1010LP4E DEMOBOARD
U2790B ATR2406-PNQW EKIT01-HMC1197LP7F Si4705-D60-EVB Si4835-Demo LMV228SDEVAL SKYA21001-EVB SMP1331-08
EVB EV1HMC618ALP3 EV1HMC641ALC4 EV1HMC8410LP2F EVAL_PAN4555ETU EVAL01-HMC1041LC4 EVAL-ADF7012DBZ2